

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

OFFICIAL

Applicant: Gautam V. Thakar, et al.

Art Unit: 2812

Serial No.: 10/645,032

Examiner: Walter L. Lindsay, Jr.

Filed: 08/21/03

Docket: T1-32822.1

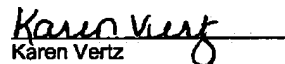
For: Polysilicon Processing Using an Anti-Reflective Dual Layer Hardmask for  
193 nm Lithography

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by facsimile to  
the U.S. Patent and Trademark Office at 703-872-9306 on the date shown  
below:

  
Karen Vertz

5-24-04  
Date

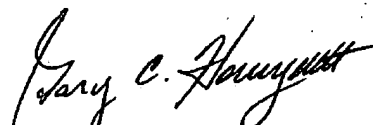
ELECTION

This election is offered in response to the Examiner's restriction requirement  
mailed April 23, 2004.

Applicants hereby provisionally elect to pursue the first invention with Claims 19-  
21, drawn to an anti-reflective coating, classified in class 257, subclass 1+.

Respectfully submitted,

Texas Instruments Incorporated  
P.O. Box 655474, M/S 3999  
Dallas, TX 75265  
(972) 470-0130

  
Gary C. Honeycutt  
Attorney for Applicants  
Registration No. 20,250

To: Facsimile Number: 703-872-9306  
From: Texas Instruments Incorporated  
Facsimile: 972-917-4418

Total Pages Sent 2  
**RECEIVED**  
CENTRAL FAX CENTER  
MAY 24 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**OFFICIAL**

In re the Application of

Applicant Gautam V. Thakar, et al.

Docket Number: TI-32822.1

Serial No.: 10/645,032

Art Unit: 2812

Filed: 08/21/03

Examiner: Walter L. Lindsay, Jr.

For: Polysilicon Processing Using an Anti-Reflective Dual Layer  
Hardmask for 193 nm Lithography

**CERTIFICATION OF FACSIMILE TRANSMISSION**

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office on the date shown below:

Karen Vertz  
Karen Vertz

5-24-04  
Date

**FACSIMILE COVER SHEET**

<input checked="" type="checkbox"/> <b>FACSIMILE COVER SHEET</b>	<input type="checkbox"/> <b>AMENDMENT</b> (# Pages)
<input type="checkbox"/> <b>NEW APPLICATION</b>	<input type="checkbox"/> <b>EOT</b>
<input type="checkbox"/> <b>DECLARATION</b>	<input type="checkbox"/> <b>NOTICE OF APPEAL</b>
<input type="checkbox"/> <b>ASSIGNMENT</b>	<input type="checkbox"/> <b>APPEAL</b> (# Pages)
<input type="checkbox"/> <b>FORMAL DRAWINGS</b>	<input type="checkbox"/> <b>ISSUE FEE &amp; PUBLICATION FEE (1 Page)</b>
<input type="checkbox"/> <b>INFORMAL DRAWINGS</b>	<input type="checkbox"/> <b>REPLY BRIEF (IN TRIPLICATE) (# Pages)</b>
<input type="checkbox"/> <b>CONTINUATION APP'N</b>	<input checked="" type="checkbox"/> <b>ELECTION</b>
<input type="checkbox"/> <b>DIVISIONAL APP'N</b>	
<b>NAME OF INVENTOR(S):</b> Gautam V. Thakar, et al.	
<b>TITLE OF INVENTION:</b> Polysilicon Processing Using an Anti-Reflective Dual Layer Hardmask for 193 nm Lithography	
<b>TI FILE NO.:</b> TI-32822.1	<b>DEPOSIT ACCT. NO.:</b> 20-0668
<b>RECEIPT DATE &amp; SERIAL NO.:</b> Serial No.: 10/645,032 Filing Date: 08/21/03	
FAXED: 5-24-04 DUE: 5-23-04 ATTY/SECY: GCH/kjv	

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated  
PO Box 655474, M/S 3899  
Dallas, TX 75285-5474